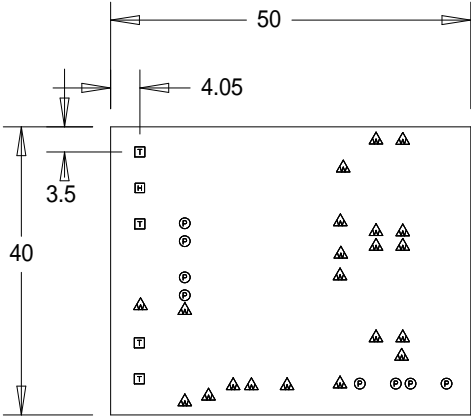


SPEC:

COMPLIANT RoHS DIRECTIVE 2011/65/UE


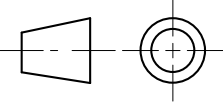
MATERIAL	FR4 IMPROVED (low CTE)
BOARD THICKNESS	1.6mm /63mils
STACKUP	SF /1LAYER
MINIMAL GAP	300um /12mils
MINIMAL SLIVER	300um /12mils
COPPER THICKNESS	35um(1oz)
FINISH THICKNESS	CHEMICAL NiAu
SOLDER MASK	GREEN BOT
SILKSCREEN	WHITE TOP&BOT
ALL BOARD ELECTRICALLY TESTED	
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK	



DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILLIMETERS

FIGURE	SIZE	PLATED	QTY
⊙	0.8		8
▲	1.0		21
▣	1.4		4
⊞	1.3		1

		W08/2013
indice	Description	Date
Controle par :		Autorise par:
 ON semiconductor	Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE	
	Subc. DYPE TECH	Dessine: e B Echelle: 1/1
Board: Pre-Regulator For Ultra Wide Vin SMPS		Pages: 1/3
CE DOCUMENT EST LA PROPRIETE DE ON semiconductor IL NE PEUT ETRE UTILISER, REPRODUIT OU COMMUNIQUER SANS SONT AUTHORISATION		Format: A3
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